PCN Number: 202		21021002.1				Ρ		Date:	October 21, 2022			
Title:Qualification of RFAB as an additional Fab site option for select LBC8 devices												
Customer Contact:				<u>PCN</u>	<u>Manager</u>				ept:		Quality Services	
Proposed 1 <sup>st</sup> Ship Date:				Jan 21, 2023			Sample Requests accepted until:				Nov 21, 2022	
*Sample r	reque	sts receiv	/ed a	after November 21, 2022 will n				not	ot be supported.			
Change Ty												
Assembly Site				Assembly Process						Assembly Materials		
Design				Electrical Specification						Mechanical Specification		
Test Site				Packing/Shipping/Labeling Wafer Bump Material				g		Test Process Wafer Bump Process		
Wafer Bump SiteWafer Fab Site				Wafer Fab Materials					Wafer Fab Process			
		0100			Part number change					Waren	1001100000	
Notification Details												
Description of Change:												
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.												
	Cı	urrent Fal	o Site	9			Α	ddit	iona	l Fab S	ite	
Current Site	Current Fab Process Site		s	Wafer Diameter		New I Site		Process			Wafer Diameter	
MIHO8	3	LBC8		200 mm		RFA		LBC8			300 mm	
Qual details are provided in the Qual Data Section.												
Reason for Change:												
Continuity of supply.												
Anticipate	Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None.												
Changes t	Changes to product identification resulting from this PCN:											
Fab Site I	nform	nation:										
Chip Si		Chip Sit		-	ode (20L)	Chip	Site Co			de (21	<u> </u>	
				MH8			JPN				Ibaraki	
RFAB				RFB			USA				Richardson	
Sample product shipping label (not actual product label)												
Product Affected:												
ISO1642DWR ISO1643DWR ISO1644DWR												

## Qualification Report Approve Date 12-OCTOBER -2022

## **Qualification Results**

## Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>ISO1644DWR</u>	QBS Reference: <u>UCC23513QDWYQ1</u>	QBS Reference: <u>UCC21520ADW</u>
HAST	A2	Biased HAST	130C/85%RH 96 Hours		-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	300 Hours	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	-

QBS: Qual By Similarity

Qual Device ISO1644DWR is qualified at MSL2 260C

- Qual Device ISO1643DWR is qualified at MSL2 260C
- Qual Device ISO1642DWR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail					
WW Change Management Team	PCN ww admin team@list.ti.com					

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